

AMENDMENTS TO THE CLAIMS:

Claims 1-40 (cancelled)

41. (New) A method for removing an optical disk from a molding apparatus, wherein

the molding apparatus includes

- (i) a first mold and a second mold defining a cavity therebetween, and
- (ii) a stamper within the cavity, the stamper having data to be transferred to material that is to be molded into the optical disk within the cavity, and

the material is molded into the optical disk within the cavity when the first and second molds are in a closed position such that the stamper becomes attached to the optical disk, said method comprising:

relatively moving said first and second molds away from said closed position by a first distance such that a first release space part is formed by causing a first part of said optical disk to be separated from one of said first mold and said stamper;

supplying a gas to said first release space part such that said optical disk becomes completely separated from said one of said first mold and said stamper; then

further relatively moving said first and second molds away from said closed position by a second distance such that a second release space part is formed by causing a second part of said optical disk to be separated from the other of said first mold and said stamper, wherein a sum of said first distance and said second distance is about 0.3 mm; and

supplying a gas to said second release space part such that said optical disk becomes completely separated from said other of said first mold and said stamper.

42. (New) The method according to claim 41, wherein

said first release space part is formed by causing said first part of said optical disk to be separated from said first mold, and said second release space part is formed by causing said second part of said optical disk to be separated from said stamper.

43. (New) The method according to claim 42, wherein
supplying a gas to said second release space part comprises supplying said gas to said second release space part with a pressure of at least 24.5×10^4 Pa such that said optical disk becomes completely separated from said stamper.

44. (New) The method according to claim 43, wherein
relatively moving said first and second molds away from said closed position by a first distance such that a first release space part is formed comprises relatively moving said first and second molds away from said closed position by about 20 μm .

45. (New) The method according to claim 44, wherein
further relatively moving said first and second molds away from said closed position by a second distance such that a second release space part is formed comprises further relatively moving said first and second molds away from said closed position by at most 0.3 mm.

46. (New) The method according to claim 43, wherein
further relatively moving said first and second molds away from said closed position by a second distance such that a second release space part is formed comprises further relatively moving said first and second molds away from said closed position by at most 0.3 mm.

47. (New) The method according to claim 42, wherein
relatively moving said first and second molds away from said closed position by a first distance such that a first release space part is formed comprises relatively moving said first and second molds away from said closed position by about 20 μm .

48. (New) The method according to claim 47, wherein
further relatively moving said first and second molds away from said closed position by a second distance such that a second release space part is formed comprises further relatively moving said first and second molds away from said closed position by at most 0.3 mm.

49. (New) The method according to claim 42, wherein
further relatively moving said first and second molds away from said closed position by a second distance such that a second release space part is formed comprises further relatively moving said first and second molds away from said closed position by at most 0.3 mm.

50. (New) The method according to claim 41, wherein
said first release space part is formed by causing said first part of said optical disk to be separated from said stamper, and said second release space part is formed by causing said second part of said optical disk to be separated from said first mold.

51. (New) The method according to claim 50, wherein
supplying a gas to said first release space part comprises supplying said gas to said first release space part with a pressure of at least 24.5×10^4 Pa such that said optical disk becomes completely separated from said stamper.

52. (New) The method according to claim 51, wherein
relatively moving said first and second molds away from said closed position by a first distance such that a first release space part is formed comprises relatively moving said first and second molds away from said closed position by at most 0.3 mm.

53. (New) The method according to claim 52, wherein
further relatively moving said first and second molds away from said closed position by a second distance such that a second release space part is formed comprises relatively moving said first and second molds away from said closed position by about 20 μm .

54. (New) The method according to claim 51, wherein
further relatively moving said first and second molds away from said closed position by a second distance such that a second release space part is formed comprises relatively moving said first and second molds away from said closed position by about 20 μm .

55. (New) The method according to claim 50, wherein
relatively moving said first and second molds away from said closed position by a first distance such that a first release space part is formed comprises relatively moving said first and second molds away from said closed position by at most 0.3 mm.

56. (New) The method according to claim 55, wherein
further relatively moving said first and second molds away from said closed position by a second distance such that a second release space part is formed comprises relatively moving said first and second molds away from said closed position by about 20 μm .

57. (New) The method according to claim 50, wherein
further relatively moving said first and second molds away from said closed position by a second distance such that a second release space part is formed comprises relatively moving said first and second molds away from said closed position by about 20 μm .